

Title (en)

Method and apparatus of applying hot melt adhesive for sealing envelopes

Title (de)

Verfahren und Vorrichtung zum Beschichten von Schmelzklebstoff zum Schliessen von Briefumschlägen

Title (fr)

Procédé et dispositif pour déposer une colle thermofusible pour fermer une enveloppe

Publication

EP 1366894 A3 20040602 (FR)

Application

EP 03291251 A 20030526

Priority

FR 0206491 A 20020528

Abstract (en)

[origin: EP1366894A2] The hot-melt glue application procedure consists of delivering the molten glue through a nozzle through a nozzle (15) to the surface (13a) of a transfer roller (13), and from it to the closing flap (10a) of an envelope (1a). Variants of the design can use a cylindrical roller to which narrow strips of glue are applied for transfer to a series of envelopes moved parallel to the roller's axis, or a roller with surface projections, each receiving a layer of glue to transfer. A cold air flow can be used to set the glue after application.

IPC 1-7

B31B 19/62

IPC 8 full level

B31B 19/00 (2006.01)

CPC (source: EP US)

B31B 70/00 (2017.07 - EP); **B31B 70/62** (2017.07 - EP US); **B31B 2150/00** (2017.07 - EP); **B31B 2160/10** (2017.07 - EP US)

Citation (search report)

- [A] US 3672328 A 19720627 - KARDON EMANUEL S
- [A] NL 1008291 C2 19990813 - STRONGHOLD PAPER GROUP BV [NL]
- [A] US 5503611 A 19960402 - RICHTER KARL-HEINZ [DE], et al
- [A] US 5776285 A 19980707 - BLUEMLE MARTIN [DE]
- [A] US 3460444 A 19690812 - WINKLER RICHARD, et al
- [A] PATENT ABSTRACTS OF JAPAN vol. 014, no. 567 (M - 1059) 17 December 1990 (1990-12-17)

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE SI SK TR

DOCDB simple family (publication)

EP 1366894 A2 20031203; **EP 1366894 A3 20040602**; FR 2840240 A1 20031205; FR 2840240 B1 20040730

DOCDB simple family (application)

EP 03291251 A 20030526; FR 0206491 A 20020528